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CLIPPEDIMAGE= JP360161973A  
PAT-NO: JP360161973A  
DOCUMENT-IDENTIFIER: JP 60161973 A  
TITLE: PREPARATION OF NOVEL EPOXY RESIN  
PUBN-DATE: August 23, 1985  
INVENTOR-INFORMATION:

NAME

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NAME

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APPL-NO: JP59014860

COUNTRY

N/A

APPL-DATE: January 30, 1984

INT-CL (IPC): C07D303/14; C08G059/20 ; C08G065/32 ;  
C08G065/14

ABSTRACT:

NEW MATERIAL: An epoxy compound expressed by formula I  
[R<SB>1</SB> is organic  
compound residue having 1 active H atoms; n<SB>1</SB>,  
n<SB>2</SB>...n<SB>l</SB> are integers 0~100, and the  
sum thereof is  
1~100; 1 is an integer 1~100; B is expressed by  
formula II[X is  
expressed by formula III, IV or V (R<SB>2</SB> is H, alkyl,  
alkylcarbonyl or  
arylcarbonyl)], and contains one or more groups expressed  
by formula III in the  
resin expressed by formula I ].

EXAMPLE: The compound expressed by formula VI (n is 2 on  
the average).

USE: An alicyclic epoxy resin compound, having rapidly  
curable terminal epoxy  
groups and improved heat resistance and electrical  
characteristics without  
containing chlorine, and applicable to preparation of  
large-scale integrated  
circuits (LSI) sealing materials, sealants for light  
emitting diodes (LED) and  
semiconductors and coating materials, etc.

*No  
image  
available*

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PREPARATION: An unsaturated compound expressed by formula VII (A is cyclohexane skeleton having vinyl group of formula VIII) is reacted with an epoxidizing agent, e.g. peracetic acid, if necessary in a solvent at  $-70\sim+200^{\circ}\text{C}$  to give the aimed compound expressed by formula I .

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